IN THE SPECIFICATION:

Please replace paragraph number **[0001]** with the following rewritten paragraph:

[0001] This application is a continuation of application Serial No. 10/067,728, filed February 4, 2002, ~~pending~~ now U.S. Patent 5,594,611, issued July 15, 2003, which is a continuation of application Serial No. 09/793,938, filed February 27, 2001, now U.S. Patent ~~6,363,329 B2~~ 6,363,329, issued March 26, 2002, which is a continuation of application Serial No. 09/537,839, filed March 29, 2000, now U.S. Patent ~~6,208,947 B1~~ 6,208,947, issued March 27, 2001, which is a continuation of application Serial No. 09/302,338, filed April 29, 1999, now U.S. Patent 6,067,507, issued May 23, 2000, which is a continuation of application Serial No. 08/806,442, filed February 26, 1997, now U.S. Patent 5,915,231, issued June 22, 1999, which is related to: co-pending Serial No. 08/591,238, filed January 17, 1996, now abandoned; Serial No. 08/664,109, filed June 13, 1996, now U.S. Patent 5,895,962, issued April 20, 1999; and Serial No. 08/785,353, filed January 17, 1997 now U.S. Patent 5,927,512, issued July 27, 1999.

Please replace paragraph number **[0008]** with the following rewritten paragraph:

[0008] As described in U.S. Patent No.'s 5,301,143, 5,294,812, and 5,103,166, some methods have been devised to electronically identify IC dice. Such methods take place "off" the manufacturing line, and involve the use of electrically retrievable identification (ID) codes, such as so-called "fuse ID's," programmed into individual IC dice to identify the dice. The programming of a fuse ID typically involves selectively blowing an arrangement of fuses or ~~anti~~ anti-fuses in an IC die so that when the fuses or anti-fuses are accessed, they output a selected ID code. Unfortunately, none of these methods addresses the problem of identifying and discarding accidentally assembled IC dice "on" a manufacturing line.

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Please replace paragraph number **[0010]** with the following rewritten paragraph:

[0010] In one embodiment, the method identifies and redirects IC's that have been ~~mis-~~ mis-processed, such as bad IC's identified at probe that have accidentally been assembled and packaged. The method includes storing data, such as an electronic wafer map, at probe, for example, in association with a unique identification (ID) code, such as a fuse ID, of each of the IC's. The stored data indicates a process flow within the IC manufacturing process that each of the IC's should undergo. For example, the stored data may indicate that an IC is bad and should be discarded, or that an IC is good and should be assembled and packaged.

Please replace paragraph number **[0011]** with the following rewritten paragraph:

[0011] As described above, on occasion, one or more IC's do not undergo the process flow they should undergo. For example, some bad IC's may proceed through assembly and packaging rather than being discarded. To check for IC's that have not undergone the process flow they should undergo, the present method also includes reading the ID code of each of the IC's at, for example, the opens/shorts test at the end of assembly. The data (e.g., the wafer map) stored in association with the ID code of each of the IC's is then accessed and evaluated to identify any IC's that have undergone a process flow within the IC manufacturing process that is different from the process flow their data indicates they should have undergone, such as bad IC's that have proceeded through assembly and packaging. Any IC's identified as having been ~~mis-~~ mis-processed are then redirected within the IC manufacturing process. Thus, for example, bad IC's that have been assembled and packaged may be discarded so they do not proceed to back-end testing.

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